International Conference on Soldering and Reliability

(ICSR 2013)

Toronto, Ontario, Canada
14-17 May 2013

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International Conference on Soldering and Reliability
Toronto, Ontario, Canada

Technical Program
May 15-17, 2013

Wednesday, May 15, 2013

8:00am	**Registration/Continental Breakfast**
8:50am	Opening Remarks
9:00am	**Keynote: Solder Assembly Solutions for 3D IC Packaging""""˙B#5** Charles G. Woychik, Ph.D., Invensas Corporation
9:45am	**Electroplating of Cu in TSV and Characteristics of Low Alpha Solder Bump"""˙%** JaePil Jung, Ph.D., University of Seoul
10:15am	**Microalloyed Sn-Cu Pb-free Solder for High Temperature Applications""""˙)** Keith Howell, Nihon Superior
10:45am	Break
11:15am	**Collaboration Between OEM and EMS to Combat Head on Pillowing Defects: Part 1 - AXI Capability for HoP Detection"""""˙%'** Alex Chan, Alcatel-Lucent
11:45am	**Collaboration Between OEM and EMS to Combat Head on Pillowing Defects: Part 2- Warpage Acceptance Proposal""""˙%-** Alex Chan, Alcatel-Lucent
12:15pm	**Lunch**
1:30pm	**SERDP Tin Whisker Testing and Modeling: High Temperature/High Humidity Conditions""""˙&*** Stephan Meschter, Ph.D., BAE International
2:00pm	**The Elimination of Whiskers From Electroplated Tin"""""˙(%** George Milad, Uyemura International
2:30pm	**Characterization of Hybrid Conformal Coatings Used for Mitigating Tin Whisker Growth""""˙)%** Junghyun Cho, Ph.D., State University of New York – Binghamton
3:00pm	**Break**
3:30pm	**Microstructure and Reliability of Low Ag, Bi-Containing Solder Alloys""""˙)+** Eva Kosiba, Celestica, Inc.
4:00pm	**Development of a Suitable Flux Medium for Cleanable and No-Clean Solder Pastes Based on Tin-Bismuth-Silver Alloy"""""˙*(** Emmanuelle Guene, P.E., Inventec
4:30pm	**Fracture of Lead-free Solder Joints as a Function of Strain Rate, Local End Geometry and Thickness""""˙+'** Amir Nourani, University of Toronto
5:00pm	**Session Ends**

Thursday, May 16, 2013

Time	Session
8:00am	**Registration/Continental Breakfast**
8:50am	Opening Remarks
9:00am	**Less is More – Vapor Phase - Quality Improvement Under Oxidation Free Soldering Conditions**""""˙+, Claus Zabel, ASSCON Systemtechnik Elektronik GmbH
9:30am	**Void-Free Soldering With A New Vapor-Phase With Vacuum Technology"˙, &** J. B. Byers, A-Tek LLC
10:00am	**Break**
11:00am	**Factors Affecting Stencil Aperture Design for Next Generation Ultra Fine Pitch Printing""""˙, *** Jeff Schake, DEK Printing Machines, Ltd.
11:30am	**The Potential of Stencil Technology – Choosing the Right Stencil Options to Maximize Yield and Earnings""""˙- (** Harald Grumm, Christian Koenen GMB
12:00pm	**Stencil Printing Yield Improvements""""˙%$$** Debbie Carboni, Kyzen Corporation
12:30pm	**Lunch**
1:30pm	**Statistical Methods for Discriminating Between Tin-Lead and Lead-free Solder Interconnect Failure Data in High Cycle Fatigue""""˙%$*** Joseph M. Juarez, Ph.D., Honeywell International
2:00pm	**NASA DoD Phase 2: SAC 305 and SN100C Copper Dissolution Testing**""""˙%$+ Dave Hillman, Rockwell Collins
2:30pm	**Process Control and Reliability of Reworked BGA Solder Joint""""˙%%+** Adrian Hirceaga, Creation Technologies
3:00pm	**Break**
3:30pm	**Jetting Solder Paste Opens Up New Possibilities in Your SMT Production** Nico Coenen, MYDATA""""˙%&'
4:00pm	**Converting Cable Assembly Manufacturing to Lead Free Solder""""˙%&+** Matt Kelly, P.Eng., MBA, IBM Corporation
4:30pm	**Material Selection and Parameter Optimization for Reliable TMV PoP Assembly""""˙%' (** Martin Anselm, Ph.D., Universal Instruments Corporation
5:00 pm	**Session Ends**

Friday, May 17, 2013

8:00am	**Registration/Continental Breakfast**
8:50am	Opening Remarks
9:00am	**Reliability Challenges for Bottom Termination Components"""""˙%($** Brook Sandy-Smith, Indium Corporation
9:30am	**Generalizations about Component Flatness at Elevated Temperature"""""˙%(*** Bev Christian, Ph.D., Blackberry
10:00am	**Dielectric Material Damage vs. Conductive Anodic Filament Formation**""˙%)) Paul Reid, PWB Interconnect Solutions
10:30am	Break
10:45am	**The Study of Corrosion Behavior of Cu in Sixteen Commercial Beverages by Chemical and Electrochemical Measurement"""""˙%* ,** Nancy Wang, Blackberry
11:15am	**Electronic Grade Coating for Protection of Electronic Components**""""""˙%+ - Wei Xing Hou, Ph.D., 3M Canada
11:45am	**Final Comments**